DC/DC CONVERTERS SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

- \bullet **Up to 90% Efficiency From 2.7-V to 5.4-V Input Voltage Range Because of Special Switching Topology**
- \bullet **Up to 300-mA Output Current (TPS60130 and TPS60131)**
- \bullet **No Inductors Required, Low EMI**
- \bullet **Regulated 5-V** ±**4% Output**
- \bullet **Only Four External Components Required**
- \bullet **60-**µ**A Quiescent Supply Current**
- \bullet **0.05-**µ**A Shutdown Current**
- \bullet **Load Disconnected in Shutdown**
- \bullet **Space-Saving, Thermally-Enhanced PowerPAD**- **Package**
- \bullet **Evaluation Module Available (TPS60130EVM−143)**

features applications

- \bullet **Battery-Powered Applications**
- \bullet **Three Battery Cells to 5-V Conversion or Point-of-Use 3.3 V to 5-V Conversion**
- \bullet **Lilon Battery to 5-V Conversion**
- \bullet **Portable Instruments**
- \bullet **Battery-Powered Microprocessor Systems**
- \bullet **Backup-Battery Boost Converters**
- \bullet **PDA's, Organizers, Laptops**
- \bullet **Handheld Instrumentation**
- \bullet **Medical Instruments (e.g., Glucose Meters)**
- \bullet **PCMCIA and 5-V Smart Card Supply**

description

The TPS6013x step-up, regulated charge pumps generate a 5-V ±4% output voltage from a 2.7-V to 5.4-V input voltage (three alkaline, NiCd, or NiMH batteries or one Lithium or Lilon battery). The output current is 300 mA for the TPS60130/ TPS60131 and 150 mA for the TPS60132/ TPS60133, all from a 3-V input. Only four external capacitors are needed to build a complete high efficiency dc/dc charge pump converter. To achieve the high efficiency over a wide input voltage range, the charge pump automatically selects between a 1.5x or doubler conversion mode. From a 3-V input, all ICs can start with full load current.

efficiency (TPS60130, TPS60131) typical operating circuit

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments Incorporated.

PR PRODUCTION DATA information is current as of publication date.
Products conform to specifications per the terms of Texas Instruments
standard warranty. Production processing does not necessarily include
testing of all para

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

description (continued)

The devices feature the power-saving pulse-skip mode to extend battery life at light loads. TPS60130 and TPS60132 include a low-battery comparator; TPS60131 and TPS60133 feature a power-good output. The logic shut-down function reduces the supply current to 1 μ A (max) and disconnects the load from the input. Special current-control circuitry prevents excessive current from being drawn from the battery during startup. This dc/dc converter requires no inductors and therefore EMI is of low concern. It is available in the small, thermally enhanced 20-pin PowerPAD[™] package (PWP).

AVAILABLE OPTIONS

† The PWP package is available taped and reeled. Add R suffix to device type (e.g. TPS60130PWPR) to order quanities of 2000 devices per reel.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

functional block diagram

TPS60130/TPS60132

TPS60131/TPS60133

INSTRUMENTS POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265 3 3

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

Terminal Functions

detailed description

operating principle

The TPS6013x charge pumps provide a regulated 5-V output from a 2.7-V to 5.4-V input. They deliver a maximum load current of 300 mA or 150 mA, respectively. Designed specifically for space-critical, batterypowered applications, the complete charge pump circuit requires four external capacitors. The circuit is optimized for efficiency over a wide input voltage range.

The TPS6013x charge pumps consist of an oscillator, a 1.21-V bandgap reference, an internal resistive feedback circuit, an error amplifier, high current MOSFET switches, a shutdown/startup circuit, a low-battery or power-good comparator, and a control circuit (see functional block diagrams).

The device consists of two single-ended charge pumps. These charge pumps are automatically configured to amplify the input voltage with a conversion factor of 1.5 or 2. The conversion ratio is dependent on the input voltage and load current. This assures high efficiency over a wide input voltage range and is further described in the adaptive mode switching section below.

adaptive mode switching

The ON-resistance of the MOSFETs that are in the charge path of the flying capacitors is regulated when the charge pump operates in voltage doubler mode. It is changed depending on the output voltage that is fed back into the control loop. This way, the time-constant during the charging phase can be modified and increased versus a time-constant for fully switched-on MOSFETs. The ON-resistance of both switches and the capacitance of the flying capacitor define the time constant. The MOSFET switches in the discharge path of the charge pump are always fully switched on to their minimum r_{DS(on)}. With the time-constant during charge phase being bigger than the time constant in discharge phase, the voltage on the flying capacitors stabilizes to the lowest possible value necessary to get a stable V_{Ω} .

adaptive mode switching (continued)

The voltage on the flying capacitors is measured and compared with the supply voltage \vee_{I} . If the voltage across the flying capacitors is smaller than half of the supply voltage, then the charge pump switches into the 1.5x conversion-mode. The charge pump switches back from a 1.5x conversion-mode to a voltage doubler mode if the load current in 1.5x conversion-mode can no more be delivered.

With this control mode the device runs in *doubler* -mode at low V_I and in 1.5x conversion-mode at high V_I to optimize the efficiency. The most desirable transfer mode is automatically selected depending on both V_I and $I₁$. This means that at light loads the device selects the 1.5x conversion-mode already at smaller supply voltages than at heavy loads.

The TPS60130 output voltage is regulated using the ACTIVE-CYCLE-regulation. An active cycle controlled charge pump utilizes two methods to control the output voltage. At high load currents it varies the on-resistances of the internal switches and keeps the ratio ON/OFF time (=frequency) constant. That means the charge pump runs at a fixed frequency. It also keeps the output voltage ripple as low as in linear-mode. At light loads the internal resistance and also the amount of energy transferred per pulse is fixed and the charge pump regulates the voltage by means of a variable ratio of ON-to-OFF time. In this operating point it runs like a skip mode controlled charge pump with a very high internal resistance, which also enables a low ripple in this operation mode. Since the charge pump does effectively switch at lower frequencies at light loads, it achieves a low quiescent current.

pulse-skip mode

In pulse-skip mode the error amplifier disables switching of the power stages when it detects an output higher than 5 V. The oscillator halts and the IC then skips switching cycles until the output voltage drops below 5 V. The error amplifier reactivates the oscillator and starts switching the power stages again. The pulse-skip regulation mode minimizes operating current because it does not switch continuously and deactivates all functions except bandgap reference, error amplifier, and low-battery/power-good comparator when the output is higher than 5 V. When switching is disabled from the error amplifier, the load is also isolated from the input. In pulse-skip mode, a special current control circuitry, limits the peak current. This assures moderate output voltage ripple and also prevents the device from drawing excessive current spikes out of the battery.

start-up procedure

During start-up, i.e. when ENABLE is set from logic low to logic high, the output capacitor is charged up, with a limited current, until the output voltage V_O reaches 0.8 \times V_I. When the start-up comparator detects this voltage limit, the IC begins switching. This start-up charging of the output capacitor assures a short start-up time and eliminates the need of a Schottky diode between IN and OUT. The IC starts with a maximum load, which is defined by a 16- Ω or 33- Ω resistor, respectively.

shutdown

Driving ENABLE low places the device in shutdown mode. This disables all switches, the oscillator, and control logic. The device typically draws 0.05 µA (1 µA max) of supply current in this mode. Leakage current drawn from the output is as low as 1 µA max. The device exits shutdown once ENABLE is set to a high level. The typical no-load shutdown exit time is 10 µs. When the device is in shutdown, the load is isolated from the input.

undervoltage lockout

The TPS6013x devices have an undervoltage lockout feature that deactivates the device and places it in shutdown mode when the input voltage falls below 1.6 V.

low-battery detector (TPS60130 and TPS60132)

The internal low-battery comparator trips at 1.21 V $\pm 5\%$ when the voltage on pin LBI ramps down. The battery voltage at which the comparator initiates a low battery warning at the LBO output can easily be programmed with a resistive divider as shown in Figure 3. The sum of resistors R1 and R2 is recommended to be in the 100-k Ω to 1-MΩ range.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

low-battery detector (TPS60130 and TPS60132) (continued)

LBO is an open drain output. An external pullup resistor to OUT, in the 100-kΩ to 1-MΩ range is recommended. During start-up, the LBO output signal is invalid for the first 500 us. LBO is high impedance when the device is disabled.

If the low-battery comparator function is not used, connect LBI to ground and leave LBO unconnected.

Figure 1. Programming of the Low-Battery Comparator Trip Voltage

Formulas to calculate the resistive divider for low battery detection, with $V_{LBI} = 1.15 V - 1.27 V$:

$$
R2 = 1 M\Omega \times \frac{V_{LBI}}{V_{BAT}}
$$

$$
R1 = 1 M\Omega - R2
$$

Formulas to calculate the minimum and maximum battery voltage that triggers the low battery detector:

$$
V_{BAT(min)} = V_{LBI(min)} \times \frac{R1_{(min)} + R2_{(max)}}{R2_{(max)}}
$$

$$
V_{BAT(max)} = V_{LBI(max)} \times \frac{R1_{(max)} + R2_{(min)}}{R2_{(min)}}
$$

Table 1. Recommended Values for the Resistive Divider from the E96 Series (±**1%), VLBI = 1.15 V − 1.27 V**

V _{BAT} /V	$R_1/k\Omega$	$R_2/k\Omega$	VBAT(MIN) ^{/V}		VBAT(MAX)/V	
2.7	562	453	2.548	$-5.61%$	2.877	6.57%
2.8	576	442	2.619	$-6.47%$	2.958	5.66%
2.9	590	422	2.726	-6.00%	3.081	6.26%
3.0	590	402	2.804	$-6.53%$	3.172	5.72%
3.1	604	383	2.928	$-5.56%$	3.313	6.88%
3.2	619	374	3.016	$-5.76%$	3.414	6.70%
3.3	649	374	3.106	$-5.88%$	3.518	6.62%

A 100 nF bypass capacitor should be connected in parallel to R2 if large line transients are expected. These voltage drops can inadvertently trigger the low-battery comparator and produce a wrong low-battery warning signal at the LBO pin.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

Power-Good detector (TPS60131 and TPS60133)

The PG pin is an open-drain output that is pulled low when the output is out of regulation. When the output voltage rises to about 90% of its nominal voltage, power-good output is released. PG is high impedance when the device is disabled. An external pullup resistor must be connected between PG and OUT. The pullup resistor should be in the 100 kΩ to 1 MΩ range. If the power-good function is not used, the PG-pin should remain unconnected.

Figure 2. Typical Operating Circuit Using Power-Good Comparator

absolute maximum ratings (see Note 1)†

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: V(ENABLE), V(LBI) and V(LBO/PG) can exceed V_I up to the maximum rated voltage without increasing the leakage current drawn by these inputs.

DISSIPATION RATING TABLE FREE-AIR TEMPERATURE (see Figure 1)

DISSIPATION RATING TABLE CASE TEMPERATURE (see Figure 2)

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

† Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. It is recommended not to exceed a junction temperature of 125°C.

recommended operating conditions

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

electrical characteristics at CI = 15 µ**F, C1F = C2F = 2.2** µ**F, CO = 33** µ**F, TC = −40**°**C to 85**°**C, VI = 3 V, V(FB) = VO and V(ENABLE) = VI (unless otherwise noted)**

NOTE 2: During start-up the LBO and PG output signal is invalid for the first 500 µs.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

PARAMETER MEASUREMENT INFORMATION

Figure 5. Circuit Used For Typical Characteristics Measurements

TYPICAL CHARACTERISTICS

Table of Graphs

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

TPS60130, TPS60131, TPS60132, TPS60133 REGULATED 5-V, 300 mA HIGH EFFICIENCY CHARGE PUMP **SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999**

TYPICAL CHARACTERISTICS

APPLICATION INFORMATION

capacitor selection

The TPS6013x charge pumps require only four external capacitors as shown in the basic application circuit. Their capacitance values and types are closely linked to the output current and output noise/ripple requirements. For lowest noise and ripple, low ESR (0.1Ω) capacitors should be used for input and output capacitors.

The input capacitor improves system efficiency by reducing the input impedance. It also stabilizes the input current of the power source. The input capacitor should be chosen according to the power supply used and the distance from power source to the converter IC. The input capacitor also has an impact on the output voltage ripple. The lower the ESR of the input capacitor C_i , the lower is the output ripple. C_i is recommended to be about two to four times as large as $C_{(xF)}$.

The output capacitor C_0 can be selected from 5-times to 50-times larger than $C_{(xF)}$, depending on the ripple tolerance. The larger C_o, the lower will be the output voltage ripple. C_i and C_o can be either ceramic or low-ESR tantalum; aluminum capacitors are not recommended.

Generally, the flying capacitors $C_{(XF)}$ will be the smallest. Only ceramic capacitors are recommended, due to their low ESR and because they retain their capacitance at the switching frequency. Because the device regulates the output voltage using the pulse-skip technique, a larger flying capacitor will lead to a higher output voltage ripple if the size of the output capacitor is not increased. Be aware that, depending on the material used to manufacture them, ceramic capacitors might lose their capacitance over temperature. Ceramic capacitors of type X7R or X5R material will keep their capacitance over temperature and voltage, whereas Z5U or Y5V-type capacitors will decrease in capacitance. Table 2 lists recommended capacitor values.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

capacitor selection (continued)

Table 2. Recommended Capicator Values

The TPS6013x devices are charge pumps that regulate the output voltage using pulse-skip regulation mode. The output voltage ripple is therefore dependent on the values and the ESR of the input, output and flying capacitors. The only possibility to reduce the output voltage ripple is to choose the appropriate capacitors. The lowest output voltage ripple can be achieved using ceramic capacitors because of their low ESR and their frequency characteristic.

Ceramic capacitors typically have an ESR that is more than 10 times lower than tantalum capacitors and they retain their capacitance at frequencies more than 10 times higher than tantalum. Many different tantalum capacitors act as an inductance for frequencies higher than 200 kHz. This behavior increases the output voltage ripple. Therefore the best choice for a minimized ripple is the ceramic capacitor. For applications that do not need a higher performance in output voltage ripple, tantalum capacitors with a low ESR are a possibility for input and output capacitor, but a ceramic capacitor should be connected in parallel. Be aware that the ESR of tantalum capacitors is indirectly proportional to the physical size of the capacitor.

Table 2 is a good starting point for choosing the capacitors. If the output voltage ripple is too high for the application, it can be improved by selecting the appropriate capacitors. The first step is to increase the capacitance at the output. If the ripple is still too high, the second step would be to increase the capacitance at the input.

For the TPS60130 and TPS60131, the smallest board space can be achieved using Sprague's 595D-series tantalum capacitors for input and output. However, high capacitance ceramic capacitors will become competitive in package size soon.

The smallest size for the lower-current devices TPS60132 and TPS60133 can be achieved using the suggested ceramic capacitors.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

APPLICATION INFORMATION

capacitor selection (continued)

Tables 3 and 4 lists the manufacturers of recommended capacitors. In most applications surface-mount tantalum capacitors will be the right choice. However, ceramic capacitors provide the lowest output voltage ripple due to their typically lower ESR.

MANUFACTURER	PART NUMBER	CAPACITANCE	CASE SIZE	TYPE
Taiyo Yuden	LMK212BJ105KG-T	$1 \mu F$	0805	Ceramic
	LMK212BJ225MG-T	$2.2 \mu F$	0805	Ceramic
	LMK316BJ475KL-T	$4.7 \mu F$	1206	Ceramic
	LMK325BJ106MN-T	$10 \mu F$	1210	Ceramic
	LMK432BJ226MM-T	$22 \mu F$	1812	Ceramic
AVX	0805ZC105KAT2A	$1 \mu F$	0805	Ceramic
	1206ZC225KAT2A	$2.2 \mu F$	1206	Ceramic
	TPSC475035R0600	$4.7 \mu F$	Case C	Tantalum
	TPSC156025R0500	$15 \mu F$	Case C	Tantalum
	TPSC336010R0375	$33 \mu F$	Case C	Tantalum
Sprague	595D156X0016B2T	$15 \mu F$	Case B	Tantalum
	595D226X0016B2T	$22 \mu F$	Case B	Tantalum
	595D336X0016B2T	$33 \mu F$	Case B	Tantalum
	595D336X0016C2T	$33 \mu F$	Case C	Tantalum
Kemet	T494C156K010AS	$15 \mu F$	Case C	Tantalum
	T494C226K010AS	$22 \mu F$	Case C	Tantalum
	T494C336K010AS	33 µF	Case C	Tantalum

Table 3. Recommended Capacitors

NOTE: Case code compatibility with EIA 535BAAC and CECC30801 molded chips.

Table 4. Recommended Capacitor Manufacturers

power dissipation

The power dissipated in the TPS6013x depends on output current and the mode of operation (1.5x or doubler voltage conversion mode). It is described by the following equation:

P_{DISS} = $(\frac{1}{\eta}$ –1 $)$ V_O \times I_O (Efficiency η mainly depends on V_I and also on I_O. See efficiency graphs.)

P_{DISS} must be less than that allowed by the package rating. See the absolute maximum ratings for 20-pin PWP package power-dissipation limits and deratings.

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

APPLICATION INFORMATION

board layout

Careful board layout is necessary due to the high transient currents and switching frequency of the converter. All capacitors should be soldered in close proximity to the IC. Connect ground and power ground pins through a short, low-impedance trace. A PCB layout proposal for a two-layer board is given in Figure 23. The bottom layer of the board carries only ground potential for best performance. The layout also provides improved thermal performance as the exposed lead frame is soldered to the PCB.

An evaluation module for the TPS60130 is available and can be ordered under product code TPS60130EVM-143. The EVM uses the layout shown in Figure 23.

Figure 23. Recommended PCB Layout for TPS6013X

Figure 24. Component Placement for TPS6013X EVM

IC ₁	TPS6013x
C ₁ , C ₂	Flying capacitors
C ₃ , C ₆	Input capacitors
C4, C5	Onput capacitors
C.7	Stabilization capacitor for LBI
R ₁ , R ₂	Resistive divider for LBI
R3	Pullup resistor for LBO

Table 5. Component Identification

The best performance of the converter is achieved with the additional bypass capacitors C5 and C6 at input and output. Capacitor C7 should be included if the large line transients are expected. The capacitors are not required. They can be omitted in most applications.

TPS60130, TPS60131, TPS60132, TPS60133 REGULATED 5-V, 300 mA HIGH EFFICIENCY CHARGE PUMP **SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999**

APPLICATION INFORMATION

application proposals

paralleling of two TPS6013x to deliver 600 mA total output current

Two TPS60130x devices can be connected in parallel to yield higher load currents. The circuit of Figure 25 can deliver up to 600 mA at an output voltage of 5 V. The devices can share the output capacitors, but each one requires its own transfer capacitors and input capacitor. If both a TPS60130 and a TPS60131 are used, it is possible to monitor the battery voltage with the TPS60130 using the low-battery comparator function and to supervise the output voltage with the TPS60131 using the power-good comparator. Make the layout of the charge pumps as similar as possible, and position the output capacitor the same distance from both devices.

Figure 25. Paralleling of Two TPS6013x Charge Pumps

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

APPLICATION INFORMATION

TPS6013x operated with ultra-low quiescent current

Because the output of the TPS6013x is isolated from the input when the devices are disabled, and because the internal resistive divider is disconnected in shutdown, an ultra-low quiescent current mode can be implemented. In this mode, the output voltage is sustained because the converter is periodically enabled to refresh the output capacitor. The necessary external control signal that is applied to the ENABLE-pin is generated from a microcontroller. For a necessary supply current for the system of 1 mA and a minimum supply voltage of 4.5 V with a 33-µF output capacitor, the refresh has to be done after 9 ms. Longer refresh periods can be achieved with a larger output capacitor.

Figure 26. TPS60132 in Ultra-Low Quiescent Current Mode

regulated discharge of the output capacitors after disabling of the TPS6013x

During shutdown of the charge pump TPS6013x the output is isolated from the input. Therefore the discharging of the output capacitor depends on the load and on the leakage current of the capacitor. In certain applications it is necessary to completely remove the supply voltage from the load in shutdown mode. That means the output capacitor of the charge pump has to be actively discharged when the charge pump is disabled. Figure 10 shows one solution to this problem.

Figure 27. Block Diagram of the Regulated Discharge of the Output Capacitor

SLVS258A − NOVEMBER 1999 − REVISED DECEMBER 1999

APPLICATION INFORMATION

related information

application reports

For more application information see:

- \bullet PowerPAD[™] Application Report, Literature Number SLMA002
- \bullet TPS6010x/TPS6011x Charge Pump Application Report, Literature Number SLVA070
- \bullet Powering the TMS320C5420 Using the TPS60100, TPS76918, and the TPS3305-18, Literature Number SLVA082.

device family products

Other devices in this family are:

www.ti.com 27-Aug-2009

PACKAGING INFORMATION

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is

provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS
INSTRUMENTS

TAPE DIMENSIONS

TAPE AND REEL INFORMATION

*All dimensions are nominal

TEXAS
INSTRUMENTS

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

*All dimensions are nominal

PWP (R-PDSO-G20)

PowerPAD[™] PLASTIC SMALL OUTLINE

- This drawing is subject to change without notice. В.
- Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side. C.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad D.
-
- Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding
recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. See the additional figure in the Pro E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

THERMAL INFORMATION

This PowerPADTM package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively,
can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating
abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

NOTES:

A.

- All linear dimensions are in millimeters. This drawing is subject to change without notice. **B.**
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad. C.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad D. Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads. $F_{\rm{r}}$

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated